

## LMNBSS123 100V N-Channel Enhancement Mode MOSFET

### Features

- 100V, 0.17A,  $R_{DS(ON)} = 6.0\Omega @ V_{GS} = 10V$
- SOT-23 package design
- Lead(Pb)-Free

### Product Description

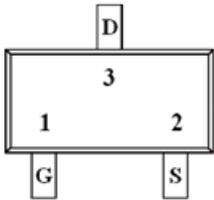
The LMNBSS123 is the N-Channel enhancement mode field effect transistors are produced using high cell density DMOS technology.

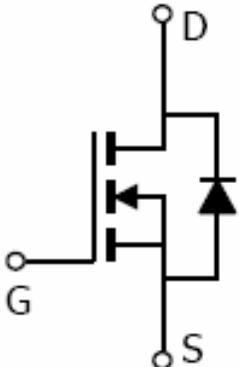
These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance.

### Applications

- DC to DC Converter
- Cellular & PCMCIA Card
- Cordless Telephone
- Power Management in Portable and Battery etc.

### Pin Configuration

LMNBSS123JZF (SOT-23)	
 <p style="text-align: center;">Top Views</p>	
Pin	Description
1	Gate
2	Source
3	Drain



**Ordering Information**

Part Number	P/N	PKG Code	Pb Free Code	Package	Quantity Reel
LMNBSS123JZF	LMNBSS123	JZ	F	SOT-23	3000 pcs

**Marking Information**

Part Marking	Part Number	LFC code
SAT	SA	T

**Absolute Maximum Ratings**

 ( $T_A=25^\circ\text{C}$  Unless otherwise noted)

Symbol	Parameter	Typical	Unit
$V_{DSS}$	Drain-Source Voltage	100	V
$V_{GSS}$	Gate-Source Voltage- Continuous	$\pm 20$	V
$V_{GSM}$	Gate-Source Voltage- Non Repetitive( $t_p \leq 50\mu\text{s}$ )	$\pm 40$	V
$I_D$	Continuous Drain Current( $T_A=25^\circ\text{C}$ )	0.17	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	0.68	A
$P_D$	Power Dissipation( $T_A=25^\circ\text{C}$ ) <sup>2</sup>	0.225	W
	Power Dissipation (Derate above $25^\circ\text{C}$ )	1.8	W/ $^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to +150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	556	$^\circ\text{C}/\text{W}$

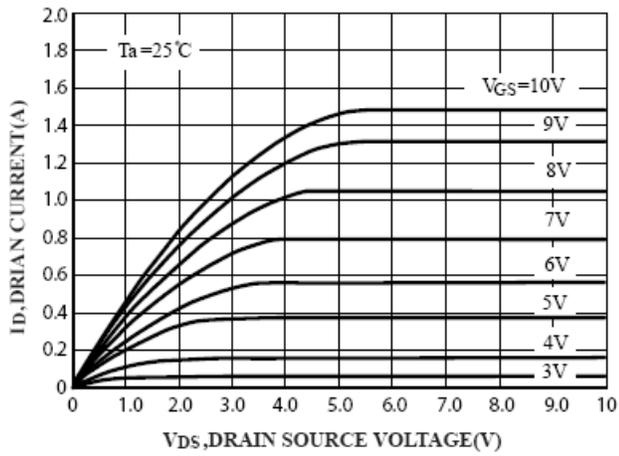
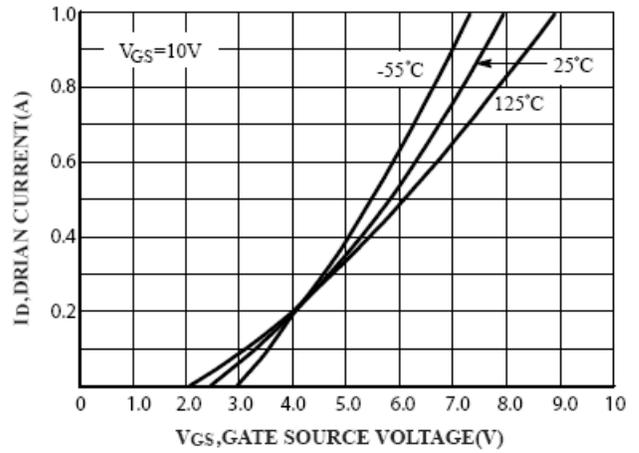
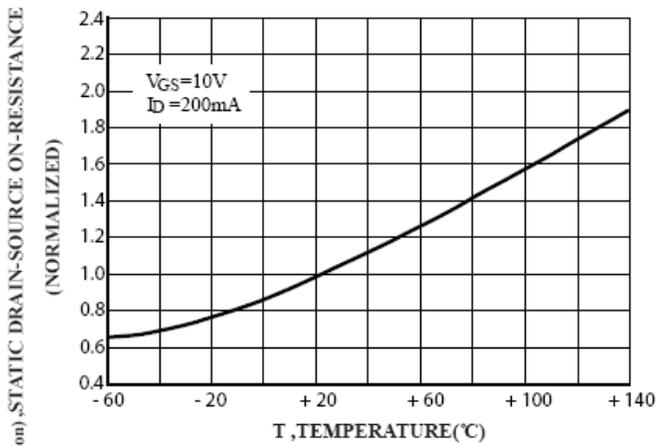
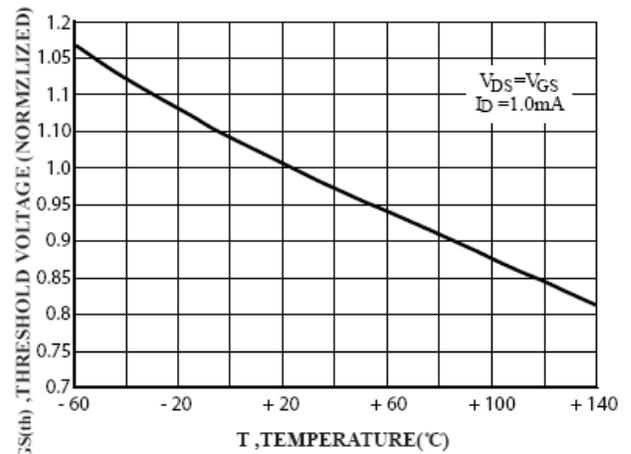
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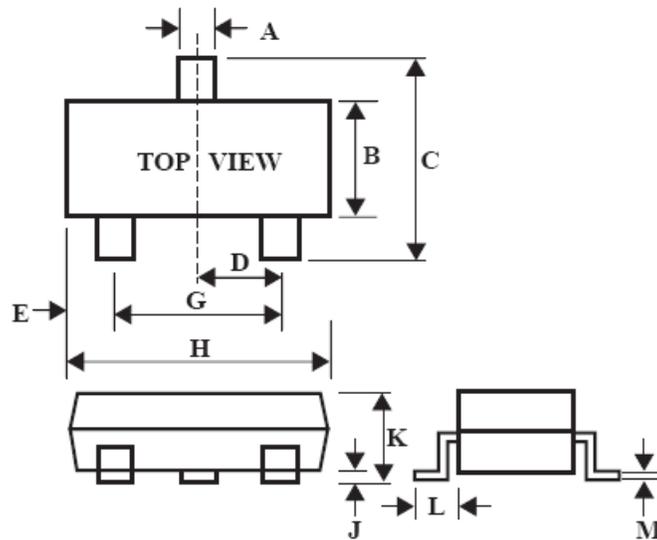
1. Pulse Test :  $PW \leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$
2. RF-5=1.0x0.75x0.062 in.

**Electrical Characteristics**

 (T<sub>A</sub>=25°C Unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =1.0mA	0.8		2.8	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			50	nA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V			15	μA
		V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C			60	
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =0.1A		5.0	6.0	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =25V, I <sub>D</sub> =0.1A	8.0			ms
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =0.34A			1.3	V
<b>Dynamic</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz		20		pF
C <sub>oss</sub>	Output Capacitance			9		
C <sub>rss</sub>	Reverse Transfer Capacitance			4		
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =30V, I <sub>D</sub> =0.28A, V <sub>GS</sub> =10V, R <sub>G</sub> =50Ω		20		ns
t <sub>d(off)</sub>	Turn-Off Time			40		

**Typical Performance Characteristics**

**FIG.1 Ohmic Region**

**FIG.2 Transfer Characteristics**

**FIG.3 Temperature Versus Static Drain-Source On-Resistance**

**FIG.4 Temperature Versus Gate Threshold Voltage**

**Package Dimension**
**SOT-23**


Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
<b>A</b>	0.350	0.510	0.014	0.020
<b>B</b>	1.190	1.400	0.046	0.055
<b>C</b>	2.100	3.000	0.082	0.118
<b>D</b>	0.850	1.050	0.033	0.041
<b>E</b>	0.460	1.000	0.018	0.039
<b>G</b>	1.700	2.100	0.066	0.082
<b>H</b>	2.700	3.100	0.106	0.122
<b>J</b>	0.010	0.130	0.000	0.005
<b>K</b>	0.890	1.100	0.035	0.043
<b>L</b>	0.300	0.610	0.011	0.024
<b>M</b>	0.076	0.250	0.003	0.010